

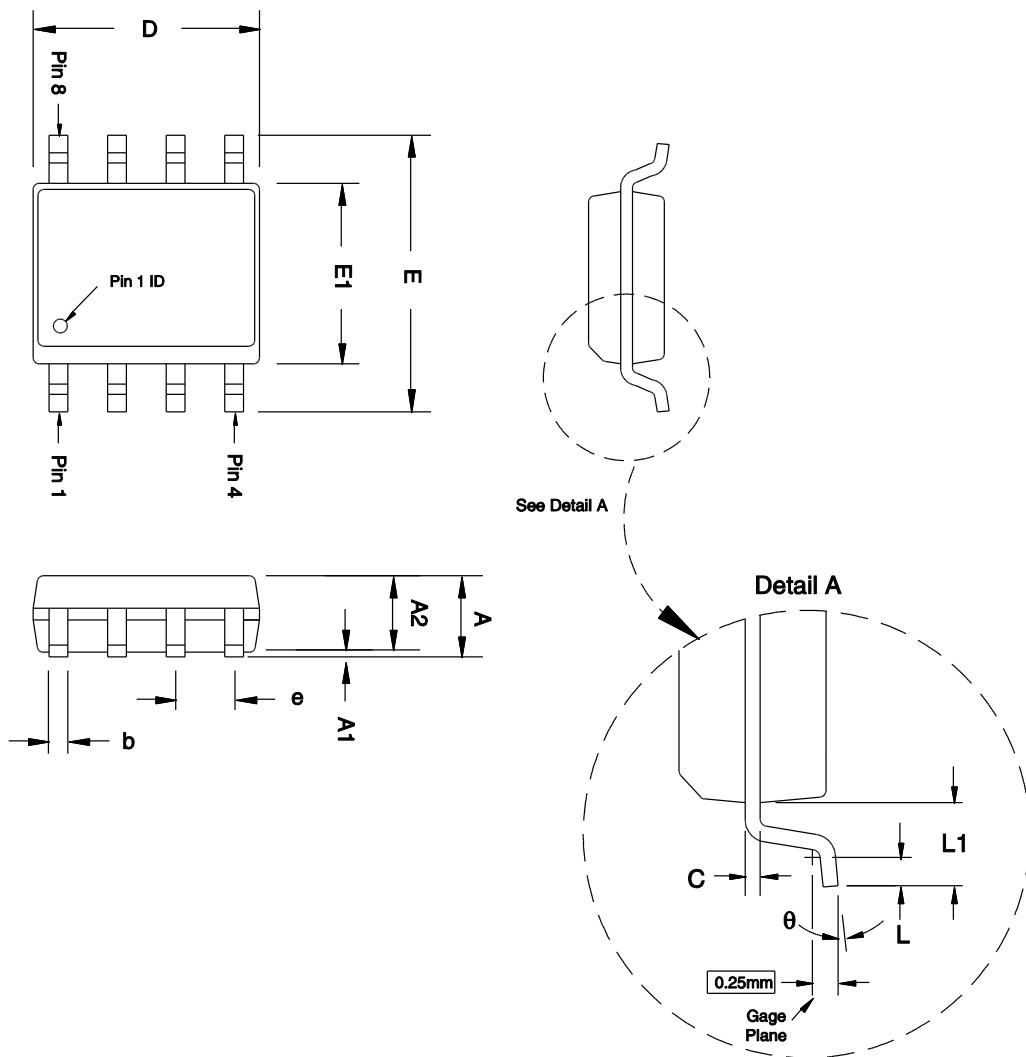
8-Pin Small Outline Integrated Circuit Package (SOIC) - Wire Bond

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin 1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	Specification
Ordering Code Reference	S
Package Acronym	SOIC
Substrate Material	Copper
Lead Finish (plating)	Pb-free: Matte Tin (Annealed)
JEDEC Outline Reference	MS-012 Variation: AA
Lead Coplanarity	0.1 mm
Weight	0.08 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	1.35	-	1.75
A1	0.10	-	0.25
A2	-	-	-
D	4.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
L	0.40	-	1.27
L1	-		
b	0.33	-	0.51
c	0.19	-	0.25
e	1.27 BSC		
θ	0°	-	10°

Package Outline



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
October 2017	1.0	Initial release



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